SPECIFICATIONS

Insulation Resistance: $10^{12}$Ω min.
Withstanding Voltage: 1,000 Volts for 1 minute
Contact Resistance: 10mΩ max. at 10mA / 20mV
Current Rating: 1A max.
Operating Temperature Range: -55°C ~ +125°C
Acceptable Pin Diameter: 0.46 ±0.05
Mating Cycles: 100 insertions min.

MATERIALS AND FINISH

Housing: PCT, 30% glass filled Polyester, UL94V-0
Contact: Inner clip – Beryllium Copper (BeCu), Au over Ni (2-3µm)
Outer sleeve – Machined Brass, Sn (5µm) over Ni (2-3µm)

FEATURES

- Custom specific pin counts with grids to 41x41
- Pin-Grid-Array precision-IC-Sockets, with displaced contacts, for picking up of ICs with high packing density.
- Contacts with 6-finger-clip, for low insertion and withdrawal forces

OUTLINE SOCKET DIMENSIONS (GRID 37 X 37)

CONTACT POSITION DETAIL

Without Stand-off pins (Standard)

With Stand-off pins

PART NUMBER

YED210 - 321 37 - 0 B S 4

Series No.
No. of Contact Pins
Grid
Design No.
Inner Contact Plating B = Gold
Outer Sleeve Plating S = Solder
Terminal Style